

AMENDMENT TRANSMITTAL LETTER (Large Entity)Applicant(s): **Chan-hoon PARK**

Docket No.

SEC.689

Serial No.

09/484,051

Filing Date

January 18, 2000

Examiner

C. Atkinson

Group Art Unit

3743Invention: **WAFER HEATING APPARATUS HAVING FLUID HEAT TRANSFER MEDIUM AND METHOD OF HEATING A WAFER USING THE SAME****TO THE ASSISTANT COMMISSIONER FOR PATENTS:**

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	9 -	20 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	3 -	3 =	0 x	\$84.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

☒ No additional fee is required for amendment.☐ Please charge Deposit Account No. _____ in the amount of _____
A duplicate copy of this sheet is enclosed.☐ A check in the amount of _____ to cover the filing fee is enclosed.☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. **50-0238**
A duplicate copy of this sheet is enclosed.☒ Any additional filing fees required under 37 C.F.R. 1.16.☒ Any patent application processing fees under 37 CFR 1.17.Dated: **11 December 2001****KENNETH D. SPRINGER**

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I certify that this document and fee is being deposited on _____ with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

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CC:



SEC.689

10/1A

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of

Chan-hoon PARK

Group Art Unit: 3743

Serial No.: 09/484,051

Examiner: C. Atkinson

Filed: January 18, 2000

For: WAFER HEATING APPARATUS HAVING FLUID HEAT TRANSFER MEDIUM
AND METHOD OF HEATING A WAFER USING THE SAME

AMENDMENT

Honorable Assistant Commission for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated 5 October 2001, please amend the application
as follows:

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In the Claims:

1. (Amended) A method of heating a wafer comprising the steps of:

generating heat to be supplied to the wafer;

transferring the heat to a liquid component of a fluid heat transfer medium in an
amount sufficient to evaporate the liquid and produce a vapor;

transferring heat from the vapor of the fluid medium to a solid heat transfer medium,
wherein the vapor is condensed back into a liquid phase; and

supporting the wafer on the solid heat transfer medium so that the wafer is heated
with the heat which has been transferred from the vapor of the fluid heat transfer medium to